

**Features:**

- Isolated mounting base 3000V~
- Solder joint technology with increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V_{RSM}	V_{RRM}	Type & Outline
900V	800V	MDx160-08-229H3
1100V	1000V	MDx160-10-229H3
1300V	1200V	MDx160-12-229H3
1500V	1400V	MDx160-14-229H3
1700V	1600V	MDx160-16-229H3
1900V	1800V	MDx160-18-229H3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_j(^{\circ}\text{C})$	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_C=100^{\circ}\text{C}$	150			160	A
$I_{F(RMS)}$	RMS forward current					251	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			12	mA
I_{FSM}	Surge forward current	10ms half sine wave $V_R=0.6V_{RRM}$	150			4	kA
I^2t	I^2t for fusing coordination					80	$\text{A}^2\text{s}\cdot 10^3$
V_{FO}	Threshold voltage		150			0.85	V
r_F	Forward slope resistance					1.25	$\text{m}\Omega$
V_{FM}	Peak forward voltage	$I_{FM}=480\text{A}$	25			1.50	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.20	$^{\circ}\text{C}/\text{W}$
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled per chip				0.08	$^{\circ}\text{C}/\text{W}$
V_{iso}	Isolation voltage	50Hz, R.M.S, $t=1\text{min}$, $I_{iso}:1\text{mA}(\text{max})$		3000			V
F_m	Terminal connection torque(M6)			4.5		6	N·m
	Mounting torque(M6)			4.5		6	N·m
T_{stg}	Stored temperature			-40		125	$^{\circ}\text{C}$
W_t	Weight				165		g
Outline	229H3						

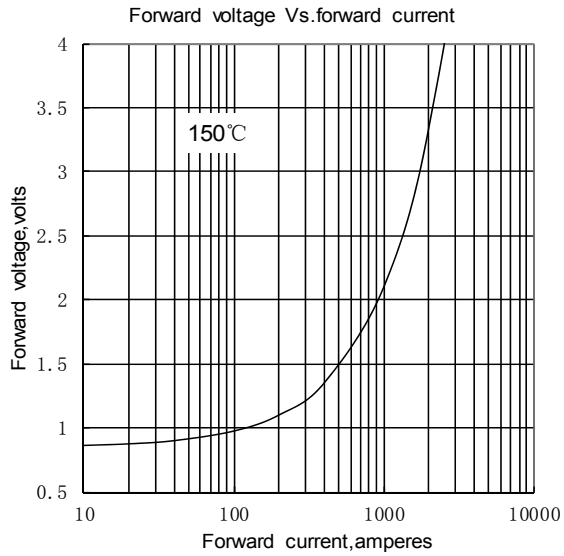


Fig1

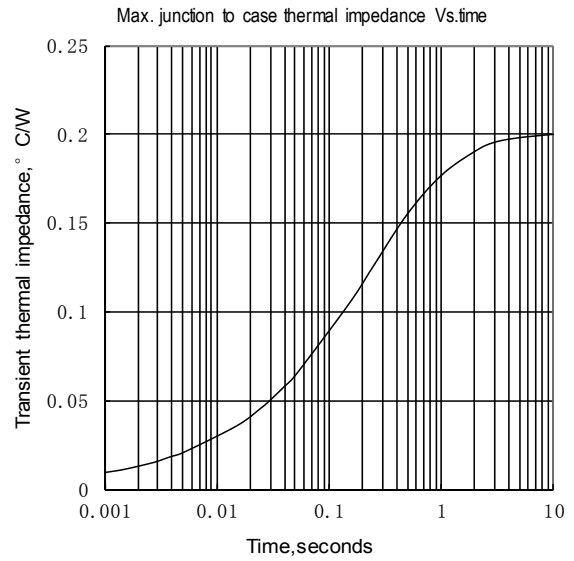


Fig2

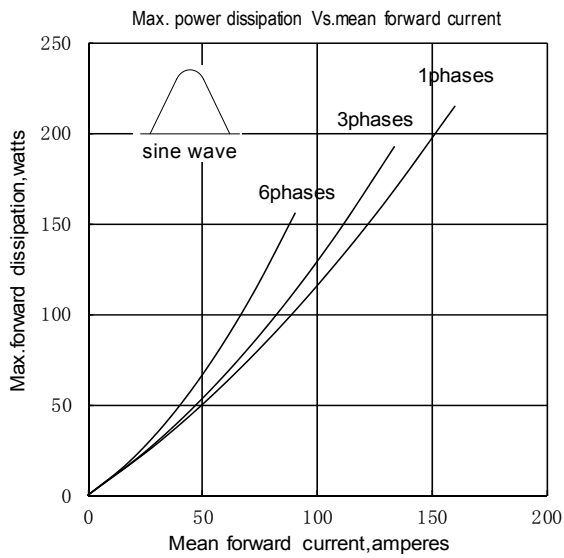


Fig3

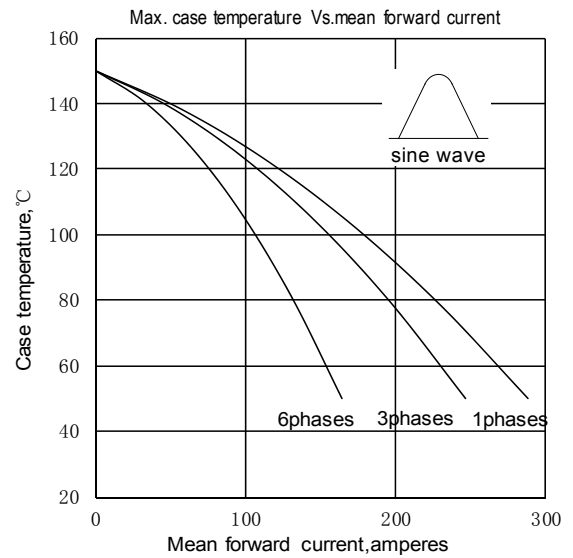


Fig4

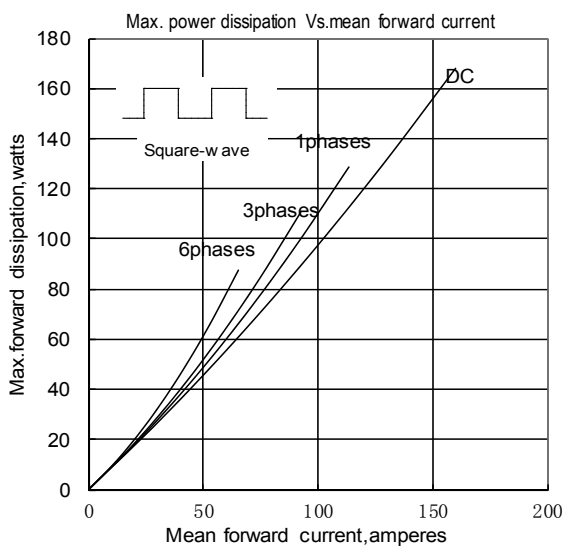


Fig5

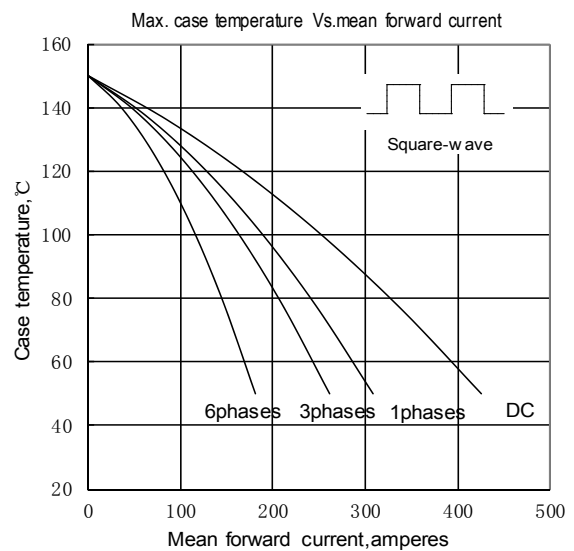


Fig6

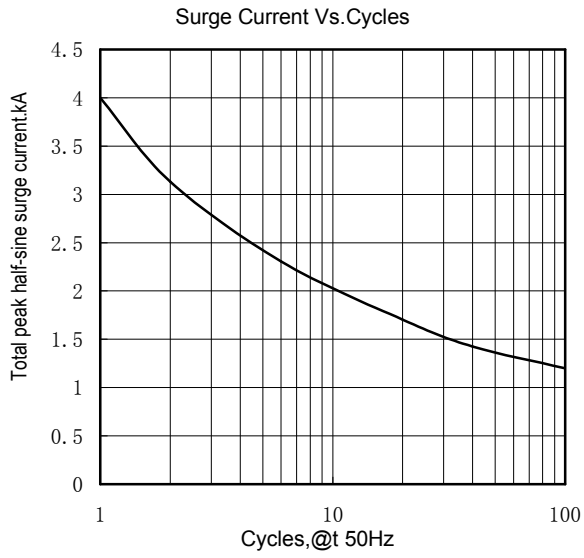


Fig7

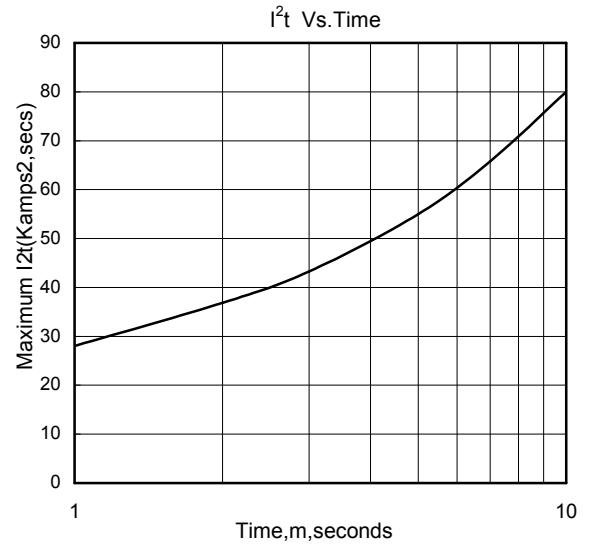


Fig8

Outline:

